

Title (en)  
EPOXY RESIN COMPOSITION AND SEMICONDUCTOR SEALING MATERIAL COMPRISING SAME

Publication  
**EP 0379172 A3 19920226 (EN)**

Application  
**EP 90100919 A 19900117**

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Abstract (en)  
[origin: EP0379172A2] Disclosed is an epoxy resin composition comprising, as basic components, (A) an epoxy resin, (B) a phenol-novolak resin, (C) a curing promotor and (D) a filler. Pulverized or spherical silica having specific particle size characteristics is used as the filler (D). Preferably, a halogenated epoxy resin and antimony oxide are further incorporated in this epoxy resin. This epoxy resin composition shows a very small molding shrinkage. If a dialkylurea derivative is used as the curing promotor (C), the stability of the composition at about 100 DEG C is drastically improved and the flowability of the composition is improved. Accordingly, precision injection molding becomes possible, and the effect of sealing a semiconductor is enhanced.

IPC 1-7  
**C08L 63/04**; **C08G 59/44**; **C08K 3/34**; **C08K 3/20**; **H01L 23/29**; **C08G 59/40**

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**C08G 59/00** (2006.01); **C08G 59/40** (2006.01); **C08G 59/62** (2006.01); **C08G 59/68** (2006.01); **C08K 3/36** (2006.01); **C08K 7/18** (2006.01); **C08L 63/00** (2006.01); **H01B 3/40** (2006.01); **H01L 23/29** (2006.01); **H01L 23/31** (2006.01)

CPC (source: EP KR US)  
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• [E] EP 0372983 A2 19900613 - SUMITOMO BAKELITE CO [JP]  
• [X] FR 2061055 A5 19710618 - CIBA GEIGY  
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